

# Programmable $V_{COM}$ Calibrator with EEPROM and Output Buffer

#### ISL24211

The ISL24211 is an 8-bit programmable current sink that can be used in conjunction with an external voltage divider to generate a voltage source ( $V_{COM}$ ) positioned between the analog supply voltage and ground. The current sink's full-scale range is controlled by an external resistor,  $R_{SET}$ . With the appropriate choice of external resistors  $R_1$  and  $R_2$ , the  $V_{COM}$  voltage range can be controlled between any arbitrary voltage range. The ISL24211 has an 8-bit data register and 8-bit EEPROM for storing both a volatile and a permanent value for its output, with an  $I^2C$  interface to read and write to the register and EEPROM. After the part is programmed, the  $I^2C$  interface is no longer needed; on power-up the EEPROM contents are automatically transferred to the data register, and the pre-programmed output voltage appears on the VCOM\_OUT pin.

The ISL24211 also features an integrated, wide-bandwidth, high output drive buffer amplifier that can directly drive the  $V_{\mbox{COM}}$  input of an LCD panel.

The ISL24211 is available in an 10 Ld 3mm x 3mm TDFN package. This package has a maximum height of 0.8mm for very low profile designs. The ambient operating temperature range is -40°C to +85°C.

### **Features**

- 8-bit, 256-Step, Adjustable Sink Current Output
- 60MHz V<sub>COM</sub> Buffer/Amplifier
- 4.5V to 19.0V Analog Supply Range for Normal Operation (10.8V Minimum Analog Supply Voltage for Programming)
- 2.25V to 3.6V Logic Supply Voltage Operating Range
- 400kHz. I<sup>2</sup>C Interface
- On-Chip 8-Bit EEPROM
- · Guaranteed Monotonic Over-Temperature
- Compatible with applications using the 7-bit ISL45041
- Pb-free (RoHS-compliant)
- Ultra-Thin 10 Ld TDFN (3 x 3 x 0.8mm max)

## **Applications**

- LCD Panel V<sub>COM</sub> Generator
- Electrophoretic Display V<sub>COM</sub> Generator

#### **Related Literature**

• AN1627 "ISL24211IRTZ-EVALZ Evaluation Board User Guide"

## **Typical Application**

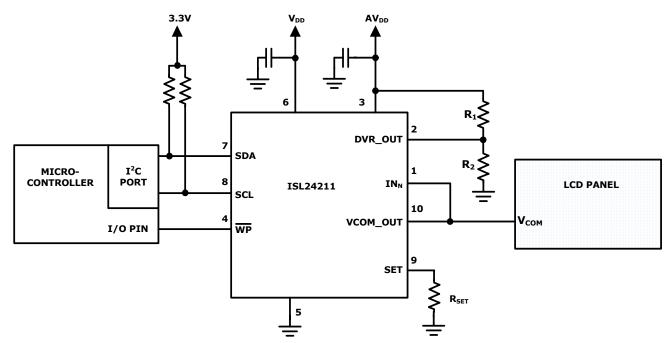


FIGURE 1. TYPICAL ISL24211 APPLICATION

## **Block Diagram**

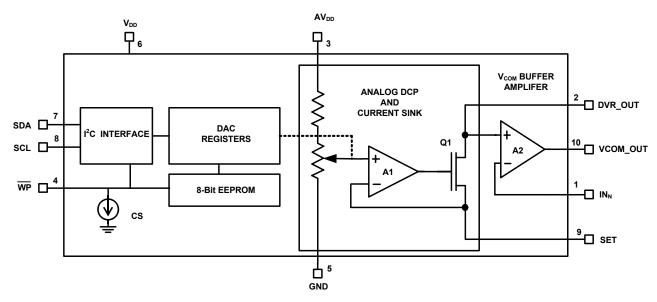


FIGURE 2. BLOCK DIAGRAM OF THE ISL24211

## **Pin Configuration**

(10 LD TDFN) **TOP VIEW** IN<sub>N</sub> 1 10 VCOM\_OUT DVR\_OUT 2 9 SET EXPOSED THERMAL PAD\* 8 SCL AV<sub>DD</sub> 3  $\overline{\mathbf{WP}}$ 7 SDA GND 5 6  $V_{DD}$ 

ISL24211

#### (\*THERMAL PAD CONNECTS TO GND)

## **Pin Descriptions**

PIN NAME	PIN NUMBER	FUNCTION
IN <sub>N</sub>	1	Negative (inverting) input of the $V_{COM}$ buffer op amp. This pin is used to provide feedback from the end point of the $V_{COM}$ trace.
DVR_OUT	2	Adjustable Sink Current Output Pin. The current sunk into the DVR_OUT pin is equal to the DAC setting times the maximum adjustable sink current divided by 256. See the "SET" pin function description below (pin 9) for the maximum adjustable sink current setting. Also tied to the non-inverting input of buffer amp.
AV <sub>DD</sub>	3	Analog Power Supply Input. Bypass to GND with 0.1µF capacitor.
WP	4	EEPROM Write Protect. Active Low.  0 = Programming disabled; 1 = Programming allowed.
GND	5	Ground connection.
V <sub>DD</sub>	6	Digital power supply input. Bypass to GND with 0.1µF capacitor.
SDA	7	I <sup>2</sup> C Serial Data Input
SCL	8	I <sup>2</sup> C Clock Input
SET	9	Maximum Sink Current Adjustment Point. Connect a resistor from SET to GND to set the maximum adjustable sink current of the DVR_OUT pin. The maximum adjustable sink current is equal to (AV <sub>DD</sub> /20) divided by R <sub>SET</sub> .
VCOM_OUT	10	Output of the buffer amplifier
PAD	-	Thermal pad should be connected to system ground plane to optimize thermal performance.

## **Ordering Information**

PART NUMBER (Notes 1, 2, 3)	PART MARKING	INTERFACE	TEMP RANGE (°C)	PACKAGE (Pb-Free)	PKG. DWG.#
ISL24211IRTZ	211Z	1 <sup>2</sup> C	-40 to +85	10 Ld 3x3 TDFN	L10.3x3A
ISL24211IRTZ-EVALZ	Evaluation Boa	rd			

#### NOTES:

- 1. Add "-T\*" suffix for tape and reel. Please refer to TB347 for details on reel specifications.
- 2. These Intersil Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.
- 3. For Moisture Sensitivity Level (MSL), please see device information page ISL24211. For more information on MSL please see techbrief TB363.

#### **Absolute Maximum Ratings**

Supply Voltage	
AV <sub>DD</sub> to GND	20V
V <sub>DD</sub> to GND	4V
Input Voltage with respect to Ground	
SET, IN <sub>N</sub>	4V
SCL, SDA and WP	V <sub>DD</sub> + 0.3V
Output Voltage with respect to Ground	
DVR_OUT, VCOM_OUT	AV <sub>DD</sub>
Continuous Output Current	
DVR_OUT	5mA
VCOM_OUT	
ESD Ratings	
Human Body Model (Tested per JESD22-A114)	7kV
Machine Model (Tested per JESD22-A115)	300V
Charged Device Model (Tested per JESD22-C101)	2kV
Latch Up (Tested per JESD 78, Class II, Level A)	100mA

#### **Thermal Information**

Thermal Resistance (Typical)	θ <sub>JA</sub> (°C/W)	θ <sub>JC</sub> (°C/W)
10 Ld TDFN Package (Notes 4, 5)	53	11
Moisture Sensitivity (see Technical Brief TB3	<u>63</u> )	
All Packages		Level 1
Maximum Die Temperature		+150°C
Storage Temperature	6	5°C to +150°C
Pb-free Reflow Profile		see link below
http://www.intersil.com/pbfree/Pb-FreeR	eflow.asp	

Recommended Operating Conditions		
Operating Range		
AV <sub>DD</sub> 4.5V to 19V		
V <sub>DD</sub>		
Ambient Operating Temperature40 °C to +85 °C		

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

#### NOTES:

- 4.  $\theta_{JA}$  is measured in free air with the component mounted on a high effective thermal conductivity test board with "direct attach" features. See Tech Brief TB379.
- 5. For  $\theta_{\mbox{\scriptsize JC}},$  the "case temp" location is the center of the exposed metal pad on the package underside.

 $\textbf{Electrical Specifications} \quad \text{Test Conditions: V}_{DD} = 3.3 \text{V}, \text{AV}_{DD} = 18 \text{V}, \text{R}_{SET} = 5 \text{k}\Omega, \text{R}_{1} = 10 \text{k}\Omega, \text{R}_{2} = 10 \text{k}\Omega, \text{(See Figure 5), V}_{COM\_OUT} \text{ pin } \text{Complete for the pin of the pi$ connected to IN<sub>N</sub>, unless otherwise specified. Typicals are at T<sub>A</sub> = +25 °C. Boldface limits apply over the operating temperature range, -40°C to +85°C.

SYMBOL	PARAMETER TEST CONDITIONS (Note 6)		TYP	MAX (Note 6)	UNITS	
DC CHARA	CTERISTICS			1		II.
V <sub>DD</sub>	V <sub>DD</sub> Supply Range - Operating		2.25		3.6	V
AV <sub>DD</sub>	AV <sub>DD</sub> Supply Range Supporting EEPROM Programming		10.8		19	V
AV <sub>DD</sub>	AV <sub>DD</sub> Supply Range for Wide-Supply Operation (not supporting EEPROM Programming)		4.5		19	V
I <sub>DD</sub>	V <sub>DD</sub> Supply Current	WP = SCL = SDA = V <sub>DD</sub>		95	300	μΑ
I <sub>AVDD</sub>	AV <sub>DD</sub> Supply Current	WP = SCL = SDA = V <sub>DD</sub>		3.8	6.5	mA
DVR_OUT	CHARACTERISTICS					
ZSE <sub>SET</sub>	SET Zero-Scale Error				±3	LSB
FSE <sub>SET</sub>	SET Full-Scale Error				±8	LSB
TCV <sub>SET</sub>	SET Voltage Drift			7		μV/°C
V <sub>DVR_OUT</sub>	DVR_OUT Voltage Range	I <sub>DVR_OUT</sub> < 0.5mA	V <sub>SET</sub> + 0.4		AV <sub>DD</sub>	V
I <sub>DVR_OUT</sub>	Maximum DVR_OUT Sink Current			4		mA
INL	Integral Non-Linearity				±2	LSB
DNL	Differential Non-Linearity				±1	LSB
OUTPUT A	MPLIFIER CHARACTERISTICS					
Vos	Input Offset Voltage			±2	±15	mV
TCV <sub>OS</sub>	Input Offset Voltage Drift			-6.3		μV/°C
IB	Input Bias Current			0.001	<b>±1</b>	μΑ
CMRR	Common-Mode Rejection Ratio		55	75		dB
PSRR	Power Supply Rejection Ratio		60	82		dB
A <sub>VOL</sub>	Open Loop Gain		55	75		dB
V <sub>OL</sub>	Output Swing Low	I <sub>L</sub> = -5mA		50	150	mV

#### ISL24211

**Electrical Specifications** Test Conditions:  $V_{DD} = 3.3V$ ,  $AV_{DD} = 18V$ ,  $R_{SET} = 5k\Omega$ ,  $R_1 = 10k\Omega$ ,  $R_2 = 10k\Omega$ , (See Figure 5),  $V_{COM\_OUT}$  pin connected to  $IN_N$ , unless otherwise specified. Typicals are at  $T_A = +25\,^{\circ}$ C. **Boldface limits apply over the operating temperature range**, **-40 °C to +85 °C.** (Continued)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 6)	ТҮР	MAX (Note 6)	UNITS
v <sub>oh</sub>	Output Swing High	I <sub>L</sub> = 5mA	17.85	17.9		٧
I <sub>SC</sub>	Short Circuit Current (Sinking)		300	430		mA
	Short Circuit Current (Sourcing)		450	555		mA
SR	Slew Rate (Rising)	1kΩ    8pF Load	70	116		V/µs
	Slew Rate (Falling)	<b>1</b> kΩ    8pF Load	50	93		V/µs
ts	Settling Time to 0.2%			150		ns
BW	-3dB Bandwidth			60		MHz
I <sup>2</sup> C INPUTS	AND OUTPUT			•		
V <sub>IH_I2C</sub>	SDA, SCL Logic 1 Input Voltage		1.44			V
V <sub>IL_I2C</sub>	SDA, SCL Logic 0 Input Voltage				0.55	V
V <sub>HYS_I2C</sub>	SDA, SCL Hysteresis			260		mV
I <sub>L_I2C</sub>	SDA, SCL Input Leakage Current				± <b>1</b>	μΑ
V <sub>OL_I2C</sub>	SDA Output Logic Low	I = -3mA			0.4	V
V <sub>IH_WP</sub>	WP Input Logic High		0.7V <sub>DD</sub>			V
V <sub>IL_WP</sub>	WP Input Logic Low				0.3V <sub>DD</sub>	V
V <sub>HYS_WP</sub>	WP Input Hysteresis			260		mV
I <sub>L_WP</sub>	WP Input Leakage Current		-0.20	-0.5	-1	μΑ
I <sup>2</sup> C TIMING	<b>i</b>					
f <sub>CLK</sub>	I <sup>2</sup> C Clock Frequency				400	kHz
t <sub>SCH</sub>	I <sup>2</sup> C Clock High Time		0.6			μs
t <sub>SCL</sub>	I <sup>2</sup> C Clock Low Time		1.3			μs
t <sub>DSP</sub>	I <sup>2</sup> C Spike Rejection Filter Pulse Width		0		50	ns
t <sub>SDS</sub>	I <sup>2</sup> C Data Set Up Time		250			ns
t <sub>SDH</sub>	I <sup>2</sup> C Data Hold Time		250			ns
t <sub>BUF</sub>	I <sup>2</sup> C Time Between Stop and Start		200			μs
tsts	I <sup>2</sup> C Repeated Start Condition Set-up		0.6			μs
t <sub>STH</sub>	I <sup>2</sup> C Repeated Start Condition Hold		0.6			μs
t <sub>SPS</sub>	I <sup>2</sup> C Stop Condition Set-up		0.6			μs
C <sub>SDA</sub>	SDA Pin Capacitance				10	pF
C <sub>SCL</sub>	SCL Pin Capacitance				10	pF
twR	EEPROM Write Cycle Time				100	ms

#### NOTE:

6. Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design.

## **Application Information**

LCD panels have a  $V_{COM}$  (common voltage) that must be precisely set to minimize flicker. Figure 3 shows a typical  $V_{COM}$  adjustment circuit using a mechanical potentiometer, and the equivalent circuit replacement using the ISL24211. Having a digital  $I^2C$  interface enables automatic, digital flicker minimization during production test and alignment. After programming, the  $I^2C$  interface has no further use therefore, the ISL24211 automatically powers up with the correct  $V_{COM}$  voltage programmed previously.

The ISL24211 uses a digitally controllable potentiometer (DCP), with 256 steps of resolution (see Figure 4) to change the current drawn at the DVR\_OUT pin, which then changes the voltage created by the  $\rm R_1$  to  $\rm R_2$  resistor divider (see Figure 5). The DVR\_OUT voltage is then buffered by A2 to generate a buffered output voltage at the  $\rm V_{COM_OUT}$  pin, capable of directly driving the  $\rm V_{COM}$  input of an LCD panel. The amount of current sunk is controlled by the setting of the DCP, which is recalled at power-up from the ISL24211's internal EEPROM. The EEPROM is typically programmed during panel manufacture. As noted in the Electrical Specifications on page 4, the ISL24211 requires a minimum AV\_DD voltage of 10.8V for EEPROM programming, but will work in normal operation (with no EEPROM programming) down to 4.5V.

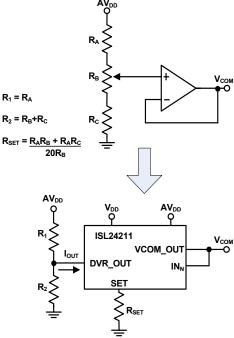


FIGURE 3. MECHANICAL ADJUSTMENT REPLACEMENT

#### **DCP (Digitally Controllable Potentiometer)**

The DCP controls the voltage that ultimately controls the SET current. Figure 4 shows the relationship between the register value and the DCP's tap position. Note that a register value of 0 selects the first step of the resistor string. The output voltage of the DCP is given in Equation 1:

$$V_{DCP} = \left(\frac{RegisterValue + 1}{256}\right) \left(\frac{AV_{DD}}{20}\right)$$
 (EQ. 1)

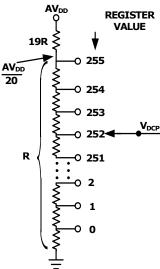


FIGURE 4. SIMPLIFIED SCHEMATIC OF DCP

#### **Output Current Sink**

Figure 5 shows the schematic of the DVR\_OUT current sink. The combination of amplifier A1, transistor Q1, and resistor R<sub>SET</sub> forms a voltage-controlled current source, with the voltage determined by the DCP setting.

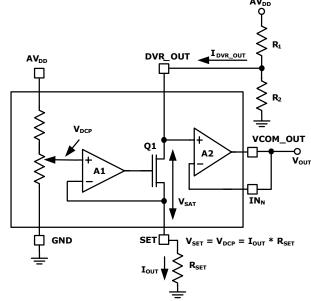


FIGURE 5. CURRENT SINK CIRCUIT

The external R<sub>SET</sub> resistor sets the full-scale (maximum) sink current that can be pulled from the DVR\_OUT node. The relationship between  $I_{DVR\_OUT}$  and Register Value is shown in Equation 2.

$$I_{DVROUT} = \frac{V_{DCP}}{R_{SET}} = \bigg(\frac{RegisterValue + 1}{256}\bigg) \bigg(\frac{AV_{DD}}{20}\bigg) \bigg(\frac{1}{R_{SET}}\bigg) \hspace{1cm} \text{(EQ. 2)}$$

The maximum value of I<sub>DVR\_OUT</sub> can be calculated by substituting the maximum register value of 255 into Equation 2, resulting in Equation 3:

$$I_{DVROUT}(MAX) = \frac{A_{VDD}}{20R_{SET}}$$
 (EQ. 3)

Equation 2 can also be used to calculate the unit sink current step size per Register Code, resulting in Equation 4:

$$I_{STEP} = \frac{AV_{DD}}{(256)(20)(R_{SET})}$$
 (EQ. 4)

#### **Determination of R<sub>SET</sub>**

The ultimate goal for the ISL24211 is to generate an adjustable voltage between two endpoints,  $V_{COM\_MIN}$  and  $V_{COM\_MAX}$ , with a fixed power supply voltage,  $AV_{DD}$ . This is accomplished by choosing the correct values for  $R_{SET}$ ,  $R_1$  and  $R_2$ . The exact value of  $R_{SET}$  is not critical. Values from 1k to more than 100k will work under most conditions. The following expression calculates the minimum  $R_{SET}$  value:

$$\mathbf{R_{SET}(MIN)} = \left(\frac{\frac{\mathbf{AV_{DD}}}{\mathbf{16}}}{\left(\mathbf{V_{OUT(MIN)}} - \frac{\mathbf{AV_{DD}}}{\mathbf{20}}\right)}\right) (\mathbf{k}\Omega)$$
 (EQ. 5)

Note that this is the absolute minimum value for R<sub>SET</sub>. Larger R<sub>SET</sub> values reduce quiescent power, since R<sub>1</sub> and R<sub>2</sub> are proportional to R<sub>SET</sub>. The ISL24211 is tested with a  $5k\Omega$  R<sub>SET</sub>.

#### Determination of R<sub>1</sub> and R<sub>2</sub>

With AV<sub>DD</sub>,  $V_{COM(MIN)}$  and  $V_{COM(MAX)}$  known and  $R_{SET}$  chosen per the above requirements,  $R_1$  and  $R_2$  can be determined using Equations 6 and 7:

$$R_{1} = 5120 \cdot R_{SET} \left( \frac{V_{COM(MAX)} - V_{COM(MIN)}}{256 \cdot V_{COM(MAX)} - V_{COM(MIN)}} \right)$$
(EQ. 6)

$${\rm R_{2}} \, = \, 5120 \cdot {\rm R_{SET}} \! \left( \frac{{\rm V_{COM(MAX)}} - {\rm V_{COM(MIN)}}}{255 \cdot {\rm AV_{DD}} + {\rm V_{COM(MIN)}} - 256 \cdot {\rm V_{COM(MAX)}}} \right) \tag{EQ. 7}$$

#### **Final Transfer Function**

The voltage at DVR\_OUT can be calculated from Equation 8:

$$V_{DVROUT} = AV_{DD} \left( \frac{R_2}{R_1 + R_2} \right) \left( 1 - \frac{RegisterValue + 1}{256} \left( \frac{R_1}{20R_{SET}} \right) \right) \tag{EQ. 8}$$

With amplifier A2 in the unity-gain configuration ( $V_{COM\_OUT}$  tied to IN<sub>N</sub> as shown in Figure 5),  $V_{DVROUT} = V_{COM\_OUT} = V_{COM}$ .

#### **Example**

As an example, suppose the A<sub>VDD</sub> supply is 15V, the desired  $V_{COM\_MIN}$ = 6.5V and the desired  $V_{COM\_MAX}$  = 8.5V. R<sub>SET</sub> is arbitrarily chosen to be 7.5k $\Omega$ .

First, verify that our chosen R<sub>SET</sub> meets the minimum requirement described in Equation 5:

$$(7.5 \text{k}\Omega) > \left( R_{\text{SET}}(\text{MIN}) = \left( \frac{\frac{15}{16}}{\left( 6.5 \text{V} - \frac{15}{20} \right)} \right) = 0.163 \text{k}\Omega \right)$$
 (EQ. 9)

Using Equations 6 and 7, calculate the values of R<sub>1</sub> and R<sub>2</sub>:

$$R_1 = 5120 \cdot 7500 \cdot \left( \frac{8.5 - 6.5}{256 \cdot 8.5 - 6.5} \right) = 35.4 \text{k}\Omega$$
 (EQ. 10)

$$\textbf{R}_2 \ = \ 5120 \cdot 7500 \cdot \left( \frac{8.5 - 6.5}{255 \cdot 15 + 6.5 - 256 \cdot 8.5} \right) \ = \ 46.4 \, \text{k}\Omega \qquad \text{(EQ. 11)}$$

Table 1 shows the resulting  $V_{COM}$  voltage as a function of register value for these conditions.

TABLE 1. EXAMPLE V<sub>DVR</sub> OUT VS REGISTER VALUE

REGISTER VALUE	V <sub>DVR_OUT</sub> (V)
0	8.49
20	8.34
40	8.18
60	8.02
80	7.87
100	7.71
120	7.55
127	7.50
140	7.40
160	7.24
180	7.09
200	6.93
220	6.77
240	6.62
255	6.50

#### **Output Voltage Span Calculation**

It is also possible to calculate  $V_{\mbox{COM}(\mbox{MIN})}$  and  $V_{\mbox{COM}(\mbox{MAX})}$  from the existing resistor values.

 $V_{COM\_MIN}$  occurs when the greatest current,  $I_{DVR(MAX)}$ , is drawn from the middle node of the R1/R2 divider. Substituting RegisterValue = 255 into Equation 8 gives the following:

$$V_{COM(MIN)} = AV_{DD} \left( \frac{R_2}{R_1 + R_2} \right) \left( 1 - \left( \frac{R_1}{20R_{SET}} \right) \right)$$
 (EQ. 12)

Similarly, RegisterValue = 0 for  $V_{COM(MAX)}$ :

$$V_{COM(MAX)} = AV_{DD} \left( \frac{R_2}{R_1 + R_2} \right) \left( 1 - \frac{1}{256} \left( \frac{R_1}{20R_{SET}} \right) \right)$$
 (EQ. 13)

By finding the difference of Equation 13 and Equation 12, the total span of  $V_{COM}$  can be found:

$$V_{COM}SPAN = AV_{DD} \left( \frac{R_2}{R_1 + R_2} \right) \left( 1 - \frac{1}{256} \right) \left( \frac{R_1}{20R_{SET}} \right)$$
 (EQ. 14)

Assuming that the I<sub>DVROUT</sub>(MIN) = 0 instead of I<sub>STEP</sub>, the expression in Equation 14 simplifies to:

$$\mathbf{V_{COM}SPAN} = \left(\frac{\mathbf{R_1} \cdot \mathbf{R_2}}{\mathbf{R_1} + \mathbf{R_2}}\right) \left(\frac{\mathbf{AV_{DD}}}{\mathbf{20R_{SET}}}\right) = \left(\frac{\mathbf{R_1} \cdot \mathbf{R_2}}{\mathbf{R_1} + \mathbf{R_2}}\right) \mathbf{I_{DVROUT}(MAX)} \tag{EQ. 15}$$

## **DVR\_OUT Pin Leakage Current**

When the voltage on the DVR\_OUT pin is greater than 10V, an additional leakage current flows into the pin in addition to the I\_SET current. Figure 6 shows the I\_SET current and the DVR\_OUT pin current for DVR\_OUT pin voltage up to 19V. In applications where the voltage on the DVR\_OUT pin will be greater than 10V, the actual output voltage will be lower than the voltage calculated by Equation 8. The graph in Figure 6 was measured with  $R_{\text{SET}} = 4.99 \text{k}\Omega$ .

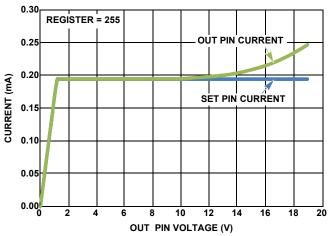


FIGURE 6. DVR\_OUT PIN LEAKAGE CURRENT

## **Power Supply Sequence**

The recommended power supply sequencing is shown in Figure 7. When applying power,  $V_{\mbox{\scriptsize DD}}$  should be applied before or at the same time as  $\mbox{\scriptsize AV}_{\mbox{\scriptsize DD}}$ . The minimum time for  $t_{\mbox{\scriptsize VS}}$  is  $\mbox{\scriptsize O}\mu s$ . When removing power, the sequence of  $\mbox{\scriptsize V}_{\mbox{\scriptsize DD}}$  and  $\mbox{\scriptsize AV}_{\mbox{\scriptsize DD}}$  is not important.

Do not remove  $V_{DD}$  or  $AV_{DD}$  within 100ms of the start of the EEPROM programming cycle. Removing power before the EEPROM programming cycle is completed may result in corrupted data in the EEPROM.

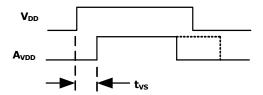


FIGURE 7. POWER SUPPLY SEQUENCE

## Operating and Programming Supply Voltage and Current

To program the EEPROM, AV<sub>DD</sub> must be ≥10.8V. If programming is not required, the ISL24211 will operate over an AV<sub>DD</sub> range of 4.5V to 19V.

During EEPROM programming,  $I_{DD}$  and  $I_{AVDD}$  will temporarily be higher than their quiescent currents. Figure 8 shows a typical  $I_{DD}$  and  $I_{AVDD}$  current profile during EEPROM programming. The current pulses are Erase and Write cycles. The EEPROM programming algorithm is shown in Figure 9. The algorithm attempts up to 4 erase cycles and 4 programming cycles, however typical parts only require 1 cycle of each, sometimes 2 when  $AV_{DD}$  is near the minimum 10.8V limit.

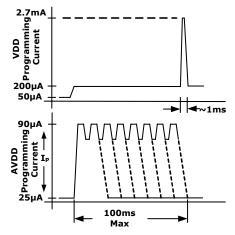


FIGURE 8.  $I_{DD}$  AND  $I_{AVDD}$  CURRENT PROFILE DURING EEPROM PROGRAMMING

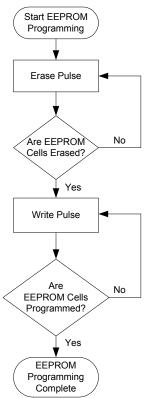


FIGURE 9. EEPROM PROGRAMMING FLOWCHART

## **ISL24211 Programming**

The ISL24211 accepts I $^2$ C bus address and data when the  $\overline{WP}$  pin is high. The ISL24211 ignores the I $^2$ C bus when the  $\overline{WP}$  pin is low. Figure 10 shows the serial data format for writing the register and programming the EEPROM. Figure 11 shows the serial data format for reading the DAC register. Table 2 shows the truth table for reading and writing the device.

**TABLE 2. ISL24211 READ AND WRITE CONTROL** 

WP PIN	R/W	P	FUNCTION
0	1	Х	Read Register.
0	0	1	Will acknowledge I <sup>2</sup> C transactions. Will not write to register.
0	0	0	Will acknowledge I <sup>2</sup> C transactions. Will not write to EEPROM.
1	1	х	Read DAC Register.
1	0	1	Write DAC Register.
1	0	0	Program EEPROM.

Programming the EEPROM memory transfers the current DAC register value to the EEPROM and occurs when the control bits select the programming mode and the  $AV_{DD}$  voltage is >10.8V. After the EEPROM programming cycle is started, the  $\overline{WP}$  pin can be returned to logic low while the EEPROM write completes, which takes a maximum of 100ms.

The ISL24211 uses a 6-bit  $I^2C$  address, which is "100111yx" for the first transmitted byte. Bit x is the  $R/\overline{W}$  bit, and Bit y is the LSB (D0) of the DCP register code to be written. The complete read and write protocol is shown in Figures 10 and 11.

## I<sup>2</sup>C Bus Signals

The ISL24211 uses fixed voltages for its  $I^2C$  thresholds, rather than the percentage of  $V_{DD}$  described in the  $I^2C$  specification (see Table 3). This should not cause a problem in most systems, but the  $I^2C$  logic levels in a specific design should be checked to ensure they are compatible with the ISL24211.

TABLE 3. ISL24211 I<sup>2</sup>C BUS LOGIC LEVELS

SYMBOL	ISL24211	I <sup>2</sup> C STANDARD		
V <sub>IL_I2C</sub>	0.55V	0.3*V <sub>DD</sub>		
V <sub>IH_I2C</sub>	1.44V	0.7*V <sub>DD</sub>		

## I<sup>2</sup>C Read and Write Format

#### ISL24211 I<sup>2</sup>C Write

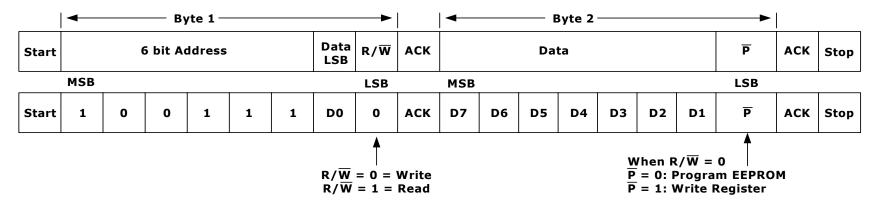
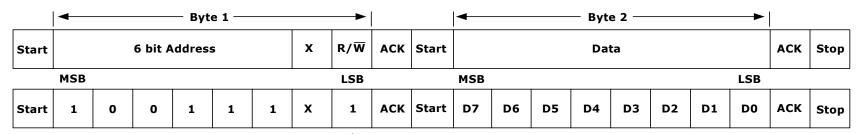


FIGURE 10. I<sup>2</sup>C WRITE FORMAT

#### ISL24211 I<sup>2</sup>C Read



 $R/\overline{W} = 0 = Write$  $R/\overline{W} = 1 = Read$ 

FIGURE 11. I<sup>2</sup>C READ FORMAT

## **Revision History**

The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest revision.

DATE	REVISION	CHANGE
2/23/11	FN7585.0	Initial Release.

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\*For a complete listing of Applications, Related Documentation and Related Parts, please see the respective device information page on intersil.com: ISL24211

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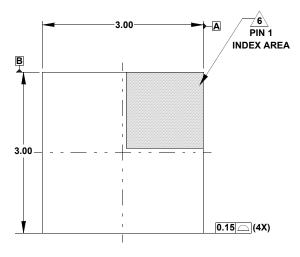
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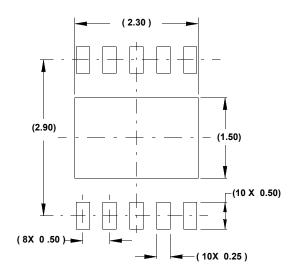
## **Package Outline Drawing**

#### L10.3x3A

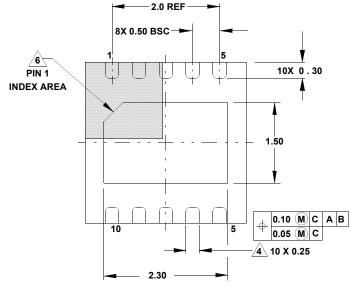
10 LEAD THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE Rev 5, 3/10



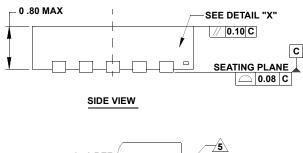
**TOP VIEW** 

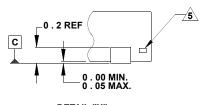


TYPICAL RECOMMENDED LAND PATTERN



**BOTTOM VIEW** 





**DETAIL "X"** 

#### NOTES:

- Dimensions are in millimeters.
   Dimensions in ( ) for Reference Only.
- 2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
- 3. Unless otherwise specified, tolerance : Decimal ± 0.05 Angular ±2.50°
- <u>A</u> Dimension applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- 5. Tiebar shown (if present) is a non-functional feature.
- The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- 7. Compliant to JEDEC MO-229-WEED-3 except exposed pad length (2.30mm).

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